# RENESAS

## HVM14S

# Silicon Epitaxial Planar PIN Diode for High Frequency Attenuator

REJ03G0113-0500Z (Previous: ADE-208-083D) Rev.5.00 Oct.08.2003

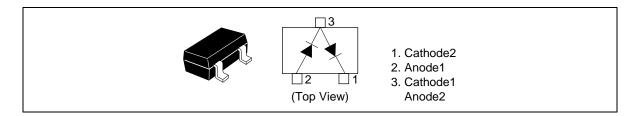
### Features

- Low forward resistance. ( $r_f = 7.0 \ \Omega \ max$ )
- Low capacitance. (C = 0.25 pF typ)
- MPAK package is suitable for high density surface mounting and high speed assembly.

## **Ordering Information**

Туре No.	Laser Mark	Package Code
HVM14S	H6	MPAK

### **Pin Arrangement**





## Absolute Maximum Ratings \*1

(Ta = 25°C)

ltem	Symbol	Value	Unit
Reverse voltage	V <sub>R</sub>	50	V
Forward current	l <sub>F</sub>	50	mA
Power dissipation	Pd	100	mW
Junction temperature	Тј	125	٥C
Storage temperature	Tstg	–55 to +125	°C

Note: 1. Absolute maximum ratings are described each unit separately.

## **Electrical Characteristics** \*<sup>1</sup>

 $(Ta = 25^{\circ}C)$ 

ltem	Symbol	Min	Тур	Мах	Unit	Test Condition
Forward voltage	VF	_	—	1.0	V	I <sub>F</sub> = 50 mA
Reverse current	I <sub>R</sub>	_	—	100	nA	V <sub>R</sub> = 50 V
Capacitance	С	—	0.25	—	pF	V <sub>R</sub> = 50 V, f = 1 MHz
Forward resistance	r <sub>f</sub>	_	—	7.0	Ω	I <sub>F</sub> = 10 mA, f = 100 MHz
ESD-Capability *2	_	200	_	_	V	C = 200 pF, Both forward and reverse direction 1 pulse.

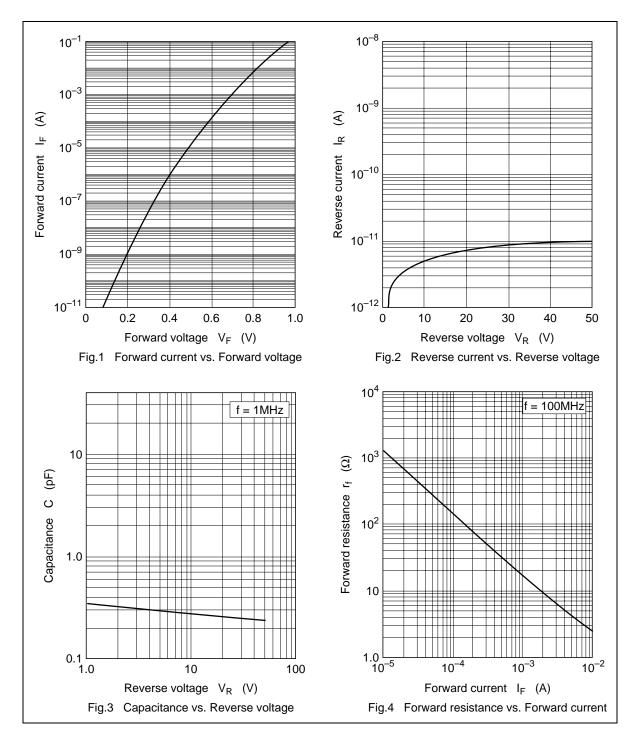
Notes: 1. Per one device.

2. Failure criterion;  $I_R \geq 200 \text{ nA}$  at  $V_R$  = 50 V



#### HVM14S

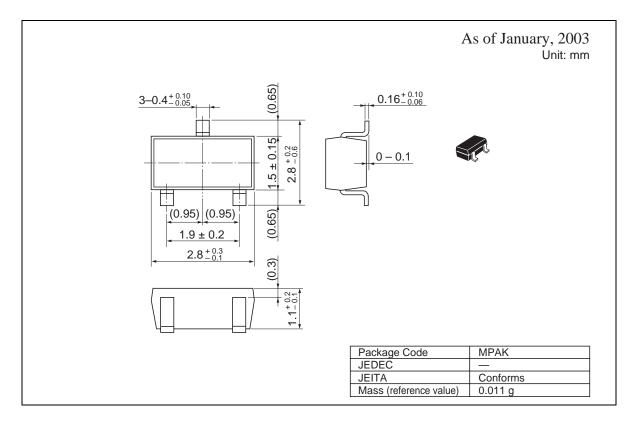
#### **Main Characteristic**



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#### HVM14S

## **Package Dimensions**





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